

### **SS12 THRU SS1200**

Reverse Voltage - 20 to 200 Volts Forward Current - 1.0 Ampere

#### SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

#### **Features**

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- Built-in strain relief,ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed:
  250 °C/10 seconds at terminals

## **Mechanical Data**

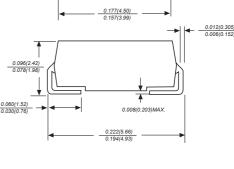
Case: JEDEC DO-214AC/SMA molded plastic body Terminals: Solderable per MIL-STD-750, Method 2026 Polarity: Color band denotes cathode end Mounting

Position: Any

Weight: 0.002 ounce, 0.07 grams

# 0.067 (1.70) 0.039 (1.00) 0.100(2.54) 0.157(3.99) 0.006(0.152)

DO-214AC/SMA





Dimensions in inches and (millimeters)

# **Maximum Ratings And Electrical Characteristics**

Ratings at 25℃ ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS12	SS13	SS14	SS15	SS16	SS18	SS110	SS1150	SS1200	UNITS
Marking Code	O I MIDOLO	MDD SS12	MDD SS13	MDD SS14	MDD SS15	MDD SS16	MDD SS18	MDD SS110	MDD SS1150	MDD SS1200	
Maximum repetitive peak reverse voltage	Vrrm	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	VRMS	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	VDC	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at TL(see fig.1)	l(AV)	1.0						А			
Peak forward surge current	I <sub>FSM</sub> 30										
8.3ms single half sine-wave						Α					
superimposed onrated load (JEDEC Method)											
Maximum instantaneous forward voltage at 1.0A	VF	0.45	0.	.55	0.70			0.85		0.9	V
Maximum DC reverse current Ta=25°C		0.5 0.2									
at rated DCblocking voltage T <sub>A</sub> =125 ℃	İR	10.0					5.0 2		2.0	mA	
Typical junction capacitance (NOTE 1)	Сл	110 80					pF				
Typical thermal resistance (NOTE 2)	Rθja	88.0					°C/W				
Operating junction temperature range	Тл	-50 to +125 -50 to +150				$^{\circ}$					
Storage temperature range	Тѕтс	-50 to +150			$^{\circ}\!\mathbb{C}$						

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C. 2.P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

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### **Typical Characterisitics**

Fig.1 Forward Current Derating Curve

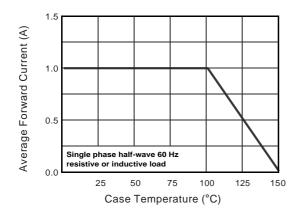


Fig.2 Typical Reverse Characteristics

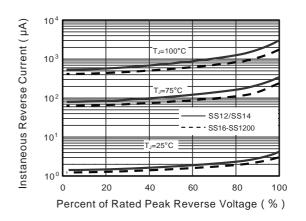


Fig.3 Typical Forward Characteristic

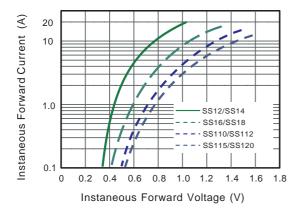


Fig.4 Typical Junction Capacitance

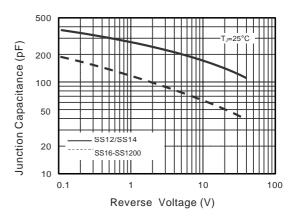


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

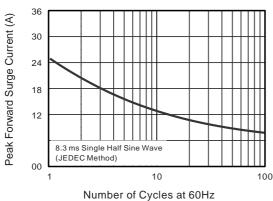
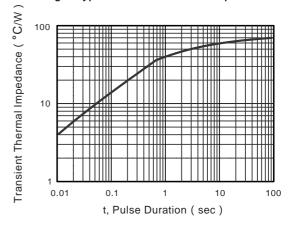


Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.

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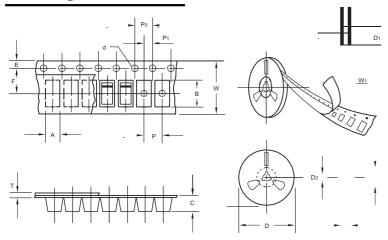


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#### **Packing information**

unit:mm



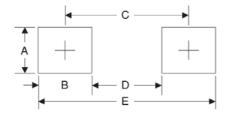
Item	Symbol	Tolerance	SMA	
Carrier width	Α	0.1	2.80	
Carrier length	В	0.1	5.33	
Carrier depth	С	0.1	2.36	
Sprocket hole	d	0.05	1.50	
13" Reel outside diameter	D	2.0	330.00	
13" Reel inner diameter	D1	min	50.00	
7" Reel outside diameter	D	2.0	178.00	
7" Reel inner diameter	D1	min	62.00	
Feed hole diameter	D2	0.5	13.00	
Sprocket hole position	Е	0.1	1.75	
Punch hole position	F	0.1	5.50	
Punch hole pitch	Р	0.1	4.00	
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00	
Embossment center	P1	0.1	2.00	
Overall tape thickness	Т	0.1	0.28	
Tape width	W	0.3	12.00	
Reel width	W1	1.0	18.00	

Note: Devices are packed in accor dance with EIA standar RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA	7"	2,000	4.0	4,000	183*155*183	178	382*356*392	80,000	16.0
SMA	11"	5,000	4.0	10,000	290*290*38	330	310*310*360	80,000	11.0
SMA	13"	7,500	4.0	15,000	335*335*38	330	350*330*360	120,000	14.5

## **Suggested Pad Layout**



Symbol	Unit (mm)	Unit (inch)
Α	1.68	0.066
В	1.52	0.060
С	3.90	0.154
D	2.41	0.095
E	5.45	0.215

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